Product Preview

MOSFET -3.5 Amps, -30 Volts

P-Channel TSOP-6

Features

- Ultra Low RDS(on)
- Higher Efficiency Extending Battery Life
- Miniature TSOP-6 Surface Mount Package

Applications

Power Management in Portable and Battery—Powered Products, i.e.:
 Cellular and Cordless Telephones, and PCMCIA Cards

MAXIMUM RATINGS (T_{.J} = 25°C unless otherwise noted.)

Rating	Symbol	Value	Unit
Drain-to-Source Voltage	V _{DSS}	-30	Volts
Gate-to-Source Voltage - Continuous	VGS	±20.0	Volts
Thermal Resistance Junction–to–Ambient (Note 1.) Total Power Dissipation @ T _A = 25°C Drain Current – Continuous @ T _A = 25°C – Pulsed Drain Current (T _p < 10 μS) Maximum Operating Power Dissipation Maximum Operating Drain Current	R _θ JA P _d I _D I _{DM} P _d I _D	62.5 2.0 -3.5 -20 1.0 -2.5	°C/W Watts Amps Amps Watts Amps
Thermal Resistance Junction—to—Ambient (Note 2.) Total Power Dissipation @ T _A = 25°C Drain Current — Continuous @ T _A = 25°C — Pulsed Drain Current (T _p < 10 μS) Maximum Operating Power Dissipation Maximum Operating Drain Current	R _θ JA Pd I _D I _{DM} Pd I _D	128 1.0 -2.5 -14 0.5 -1.75	°C/W Watts Amps Amps Watts Amps
Operating and Storage Temperature Range	T _J , T _{stg}	-55 to 150	°C
Maximum Lead Temperature for Soldering Purposes for 10 Seconds	TL	260	°C

- 1. Mounted onto a 2" square FR–4 board (1" sq. 2 oz. cu. 0.06" thick single sided), t < 5.0 seconds.
- 2. Mounted onto a 2" square FR-4 board (1" sq. 2 oz. cu. 0.06" thick single sided), operating to steady state.

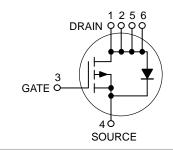


ON Semiconductor™

http://onsemi.com

-3.5 AMPERES -30 VOLTS 100 m Ω @ VGS = -10 V

P-Channel



MARKING DIAGRAM

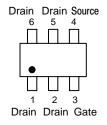


TSOP-6 CASE 318G STYLE 1



x = Date Code

PIN ASSIGNMENT



ORDERING INFORMATION

Device	Package	Shipping	
NTGS3455T1	TSOP-6	3000 Tape & Reel	

This document contains information on a product under development. ON Semiconductor reserves the right to change or discontinue this product without notice.

ELECTRICAL CHARACTERISTICS $(T_A = 25^{\circ}C \text{ unless otherwise noted})^*$

Cha	Symbol	Min	Тур	Max	Unit	
OFF CHARACTERISTICS						
Drain–Source Breakdown Voltage (V _{GS} = 0 Vdc, I _D = -10 μA)		V(BR)DSS	-30	-	-	Vdc
Zero Gate Voltage Drain Current (VGS = 0 Vdc, VDS = -30 Vdc, TJ = 25°C) (VGS = 0 Vdc, VDS = -30 Vdc, TJ = 70°C)		IDSS	_ _	_ _	-1.0 -5.0	μAdc
Gate-Body Leakage Current (VGS = -20.0 Vdc, VDS = 0 Vd	с)	IGSS	_	-	-100	nAdc
Gate–Body Leakage Current (VGS = +20.0 Vdc, VDS = 0 Vdc)		I _{GSS}	_	-	100	nAdc
ON CHARACTERISTICS						
Gate Threshold Voltage (V _{DS} = V _{GS} , I _D = -250 μAdc)		V _{GS(th)}	-1.0	-1.87	-3.0	Vdc
Static Drain–Source On–State Resistance (VGS = -10 Vdc, ID = -3.5 Adc) (VGS = -4.5 Vdc, ID = -2.7 Adc)		R _{DS(on)}	_ _	0.094 0.144	0.100 0.170	Ω
Forward Transconductance (V _{DS} = -15 Vdc, I _D = -3.5 Add	9FS	_	6.0	_	mhos	
DYNAMIC CHARACTERISTICS						
Total Gate Charge	0, 45,41, 1, 40,41	Q _{tot}	-	9.0	13	nC
Gate-Source Charge	$(V_{DS} = -15 \text{ Vdc}, V_{GS} = -10 \text{ Vdc}, I_{D} = -3.5 \text{ Adc})$	Qgs	-	2.5	_	
Gate-Drain Charge	,	Q _{gd}	-	2.0	_	
Input Capacitance	0/ 50Vd- V 0Vd-	C _{iss}	-	480	_	pF
Output Capacitance	$(V_{DS} = -5.0 \text{ Vdc}, V_{GS} = 0 \text{ Vdc}, $ f = 1.0 MHz)	Coss	-	220	_	
Reverse Transfer Capacitance	,	C _{rss}	_	60	_	
SWITCHING CHARACTERISTICS						
Turn-On Delay Time		^t d(on)	_	10	20	ns
Rise Time	$(V_{DD} = -20 \text{ Vdc}, I_D = -1.0 \text{ Adc},$	t _r	-	15	30	
Turn-Off Delay Time	$V_{GS} = -10 \text{ Vdc}, R_g = 6.0 \Omega$	td(off)	-	20	35	
Fall Time		t _f	_	10	20	
Reverse Recovery Time	$(I_S = -1.7 \text{ Adc}, dI_S/dt = 100 \text{ A/}\mu\text{s})$	t _{rr}	-	30	_	ns
BODY-DRAIN DIODE RATINGS						
Diode Forward On-Voltage	$(I_S = -1.7 \text{ Adc}, V_{GS} = 0 \text{ Vdc})$	V _{SD}	_	-0.90	-1.2	Vdc
Diode Forward On-Voltage	$(I_S = -3.5 \text{ Adc}, V_{GS} = 0 \text{ Vdc})$	V _{SD}	-	-1.0	_	Vdc

^{*}Indicates Pulse Test: P.W. = 300 μsec max, Duty Cycle = 2%.
*Class 1 ESD rated – Handling precautions to protect against electrostatic discharge is mandatory.

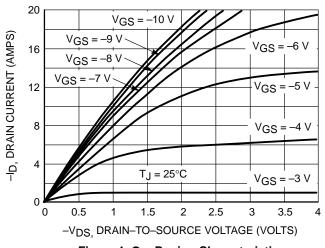


Figure 1. On-Region Characteristics

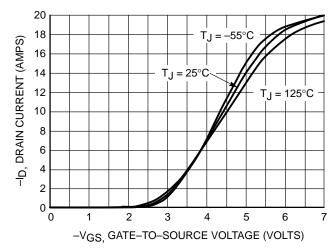


Figure 2. Transfer Characteristics

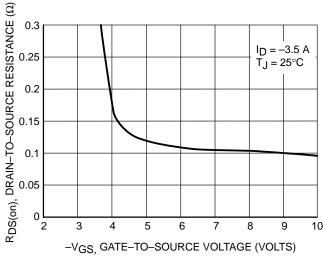


Figure 3. On-Resistance vs. Gate-to-Source Voltage

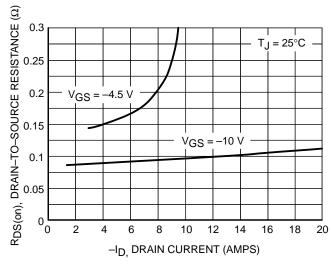


Figure 4. On-Resistance vs. Drain Current and **Gate Voltage**

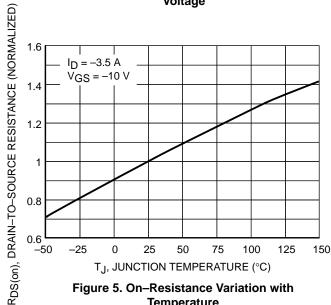


Figure 5. On-Resistance Variation with **Temperature**

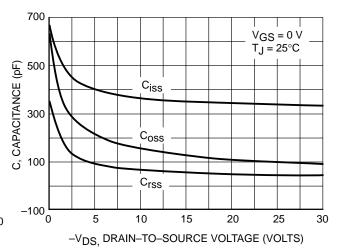
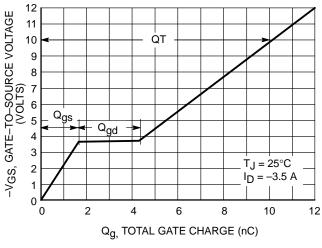


Figure 6. Capacitance Variation



| V_{GS} = 0 V |

Figure 7. Gate-to-Source and Drain-to-Source Voltage vs. Total Charge

Figure 8. Diode Forward Voltage vs. Current

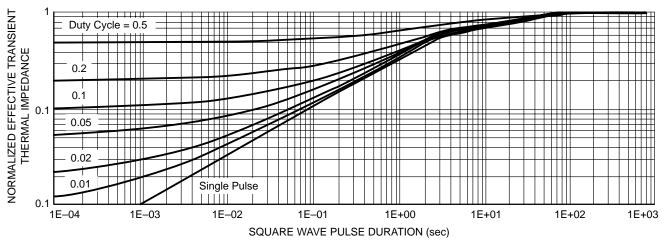


Figure 9. Normalized Thermal Transient Impedance, Junction-to-Ambient

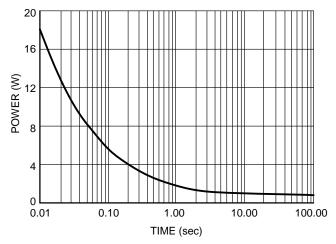
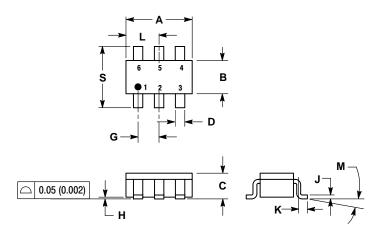


Figure 10. Single Pulse Power

PACKAGE DIMENSIONS

TSOP-6 CASE 318G-02 ISSUE G



- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: MILLIMETER.
 3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.

	MILLIMETERS		INCHES	
DIM	MIN	MAX	MIN	MAX
Α	2.90	3.10	0.1142	0.1220
В	1.30	1.70	0.0512	0.0669
С	0.90	1.10	0.0354	0.0433
D	0.25	0.50	0.0098	0.0197
G	0.85	1.05	0.0335	0.0413
Н	0.013	0.100	0.0005	0.0040
J	0.10	0.26	0.0040	0.0102
K	0.20	0.60	0.0079	0.0236
L	1.25	1.55	0.0493	0.0610
M	0 °	10°	0 °	10°
S	2.50	3.00	0.0985	0.1181

- STYLE 1:
 PIN 1. DRAIN
 2. DRAIN
 3. GATE
 4. SOURCE
 5. DRAIN
 6. DRAIN



Notes

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